

Product Change Notification / MFOL-06WDZP834

Date:

14-Jun-2022

Product Category:

Clock and Timing - High Speed Communication, PCIe - Signal Integrity

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3740.007 Final Notice: Qualification of MTAI as an additional final test site for selected VSC8115xx and VSC330xx device families available in 20L TTSOP (4.4mm) and 36L FCCSP (7x7mm) packages.

Affected CPNs:

MFOL-06WDZP834_Affected_CPN_06142022.pdf MFOL-06WDZP834_Affected_CPN_06142022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of MTAI as an additional final test site for selected VSC8115xx and VSC330xx device families available in 20L TTSOP (4.4mm) and 36L FCCSP (7x7mm) packages.

Pre and Post Change Summary:

Pre Change	Post Change

Final	Test Site	ASE Test (ASE9)	ASE Test (ASE9)	Microchip Technology Thailand(HQ) (MTAI)		
Base	Tray	416	416	416		
Quantity Multiple (BQM)	Tape and Reel	500	500	500		
Pin 1	Tray	Near tray chamfer	Near tray chamfer	Near tray chamfer		
orientation	Tape and Reel	Quadrant 1	Quadrant 1	Quadrant 1		
	Color	Black	Black	Dark Blue		
Reel	Dimension	Minor dimensional changes. See attached pre and post change comparison.				
Carrie	er Tape	No dimensional cha	anges. See attached comparison.	pre and post change		
Cove	er Tape	No dimensional changes. See attached pre and post change comparison.				
Т	ray	No dimensional cha	anges. See attached comparison.	pre and post change		
Packing	g Method	See attached	I pre and post change	e comparison.		

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity by qualifying MTAI as an additional final test site.

Change Implementation Status: In Progress

Estimated First Ship Date: August 15, 2022 (date code: 2234)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

		Jur	ne 20)22		>		Aug	ust 2	2022	
Workweek	2 3	2 4	2 5	2 6	2 7		32	33	34	35	36
Qual Report Availability			х								

Final PCN Issue Date		х				
Estimated						
Implementation					Х	
Date						

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 14, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_MFOL-06WDZP834_Qual Report.pdf PCN_MFOL-06WDZP834_Pre and Post change_summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

CCB 3740.007 Pre and Post Change Summary PCN# MFOL-06WDZP834

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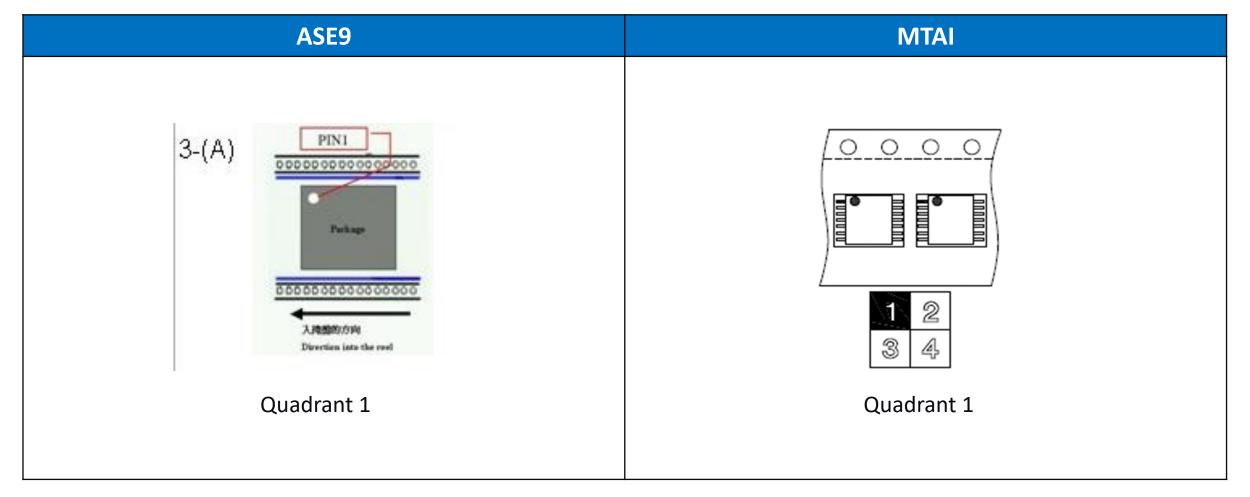


Pre and Post Summary – Base Quantity Multiple (BQM) and Pin 1 Orientation

PA	CKAGE			PRE CHANGE	PO	ST CHANGE
			Final test site	ASE Test (ASE9)	ASE Test (ASE9)	Microchip Technology Thailand (HQ) (MTAI)
20L	TTSOP	Base Quantity Multiple (BQM)	Tape and Reel	500	500	500
		Pin 1 Orientation		Quadrant 1	Quadrant 1	Quadrant 1
		Base Quantity Multiple (BQM)		416	416	416
36L	FCCSP	Pin 1 Orientation	Tray	Chamfer Tray	Chamfer Tray	Chamfer Tray
		Tray Stack		5+1	5+1	5+1

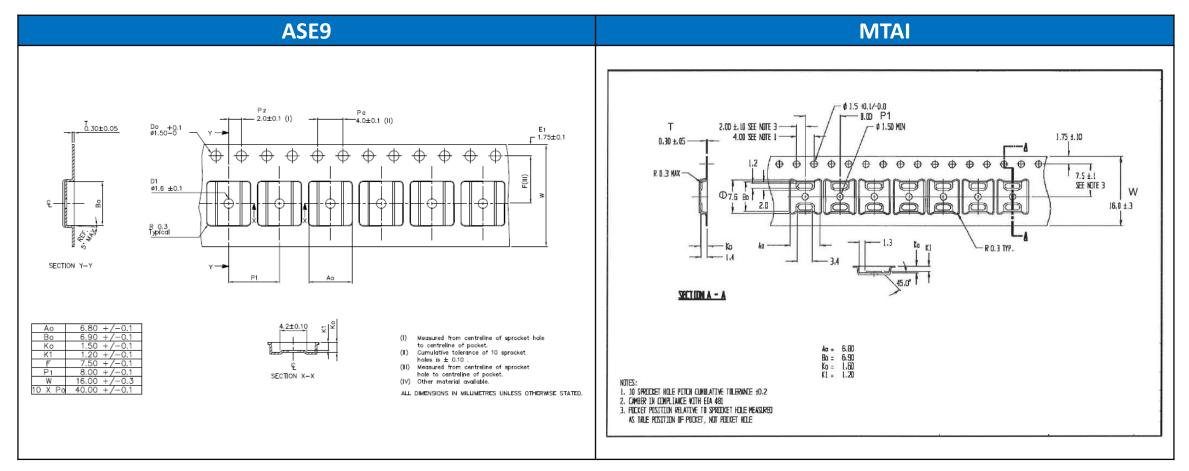


Pre and Post Change Summary – (20L TTSOP) T/R Pin 1 Orientation





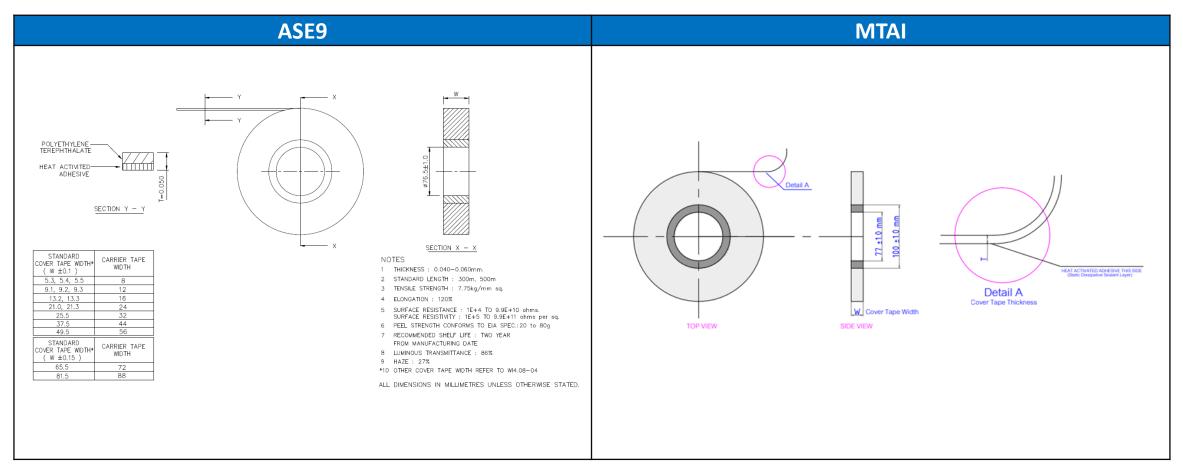
Pre and Post Change Summary – (20L TTSOP) Carrier Tape



Plant	W (mm.)	P (mm.)	A0 (mm.)	B0 (mm.)	K0 (mm.)	K1 (mm.)	Thickness	BQM	Pin1
ASE9	16.00 ±0.30	8.00 ±0.10	6.80 ±0.10	6.90 ±0.10	1.50 ±0.10	1.20 ±0.10	0.30±0.05	500	Quadrant 1
MTAI	16.00 ±0.30	8.00 ±0.10	6.80 ±0.10	6.90 ±0.10	1.60 ±0.10	1.20 ±0.10	0.30±0.05	500	Quadrant 1



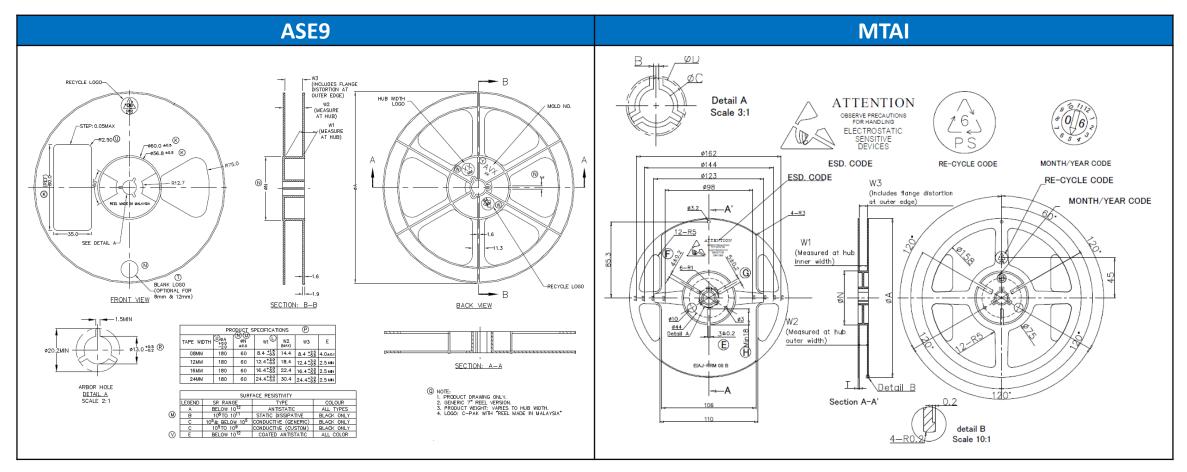
Pre and Post Change Summary – (20L TTSOP) Cover Tape



Plant	Width W (mm.)	Thickness T (mm.)	Color	Sealing Methodology
ASE9	13.3 ±0.1	0.050 ±0.010	Clear	Heat Seal
MTAI	13.3 ±0.1	0.050 ±0.010	Clear	Heat Seal



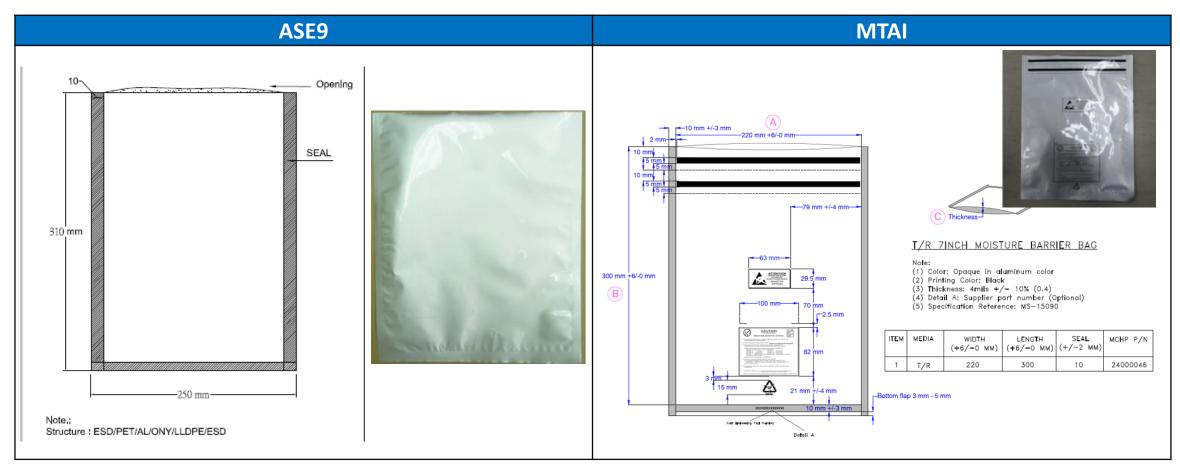
Pre and Post Change Summary – (20L TTSOP) Plastic Reel



Plant	Reel Diameter (mm.)	Reel Hub Size (mm)	Reel Width Max (mm.)	Color
ASE9	180(+0, -2)	60 ±2.0	22.40	Black
MTAI	178 ±2.0	60.5 ±0.5	22.40	Dark Blue



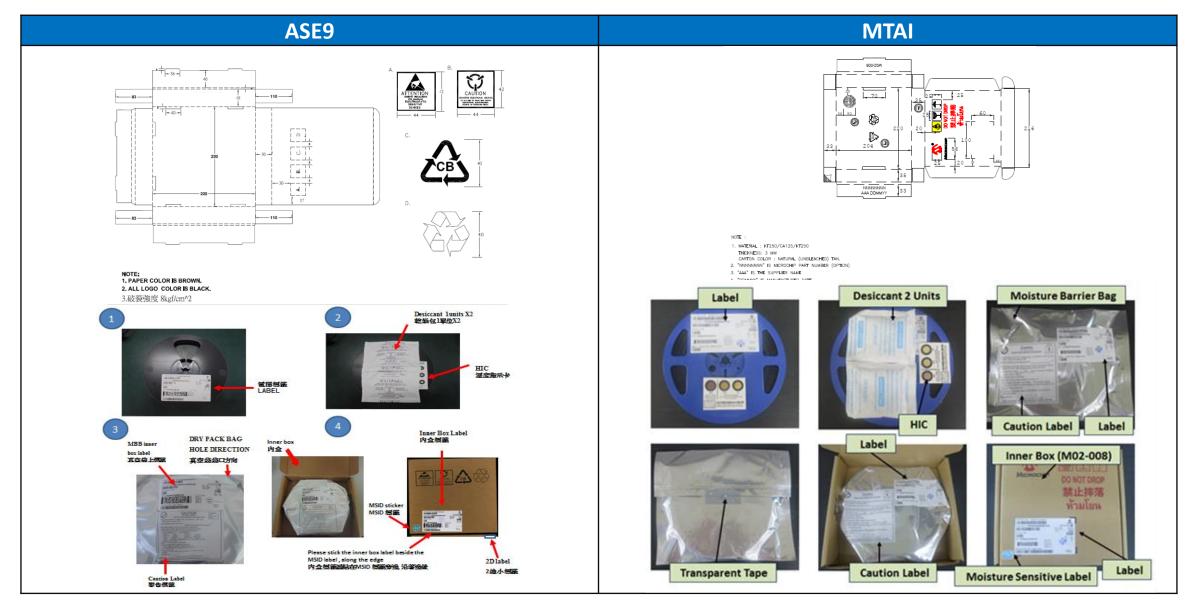
Pre and Post Change Summary – (20L TTSOP) Moisture Barrier Bag



Plant	Length (mm)	Width (mm)	Thickness (mm)	
ASE9	310	250	0.15	
MTAI	300	220	0.1016	

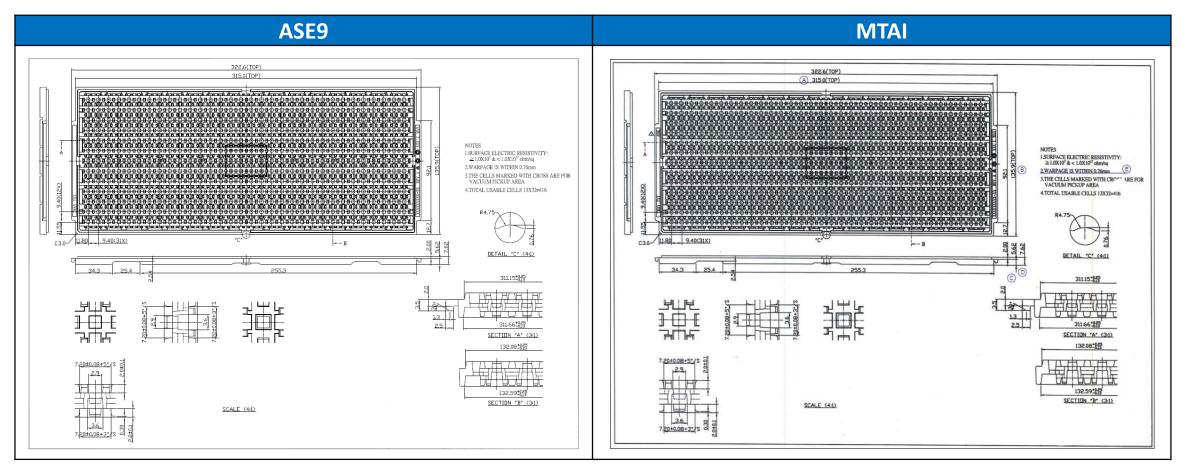


Pre and Post Change Summary – (20L TTSOP) Packing Method





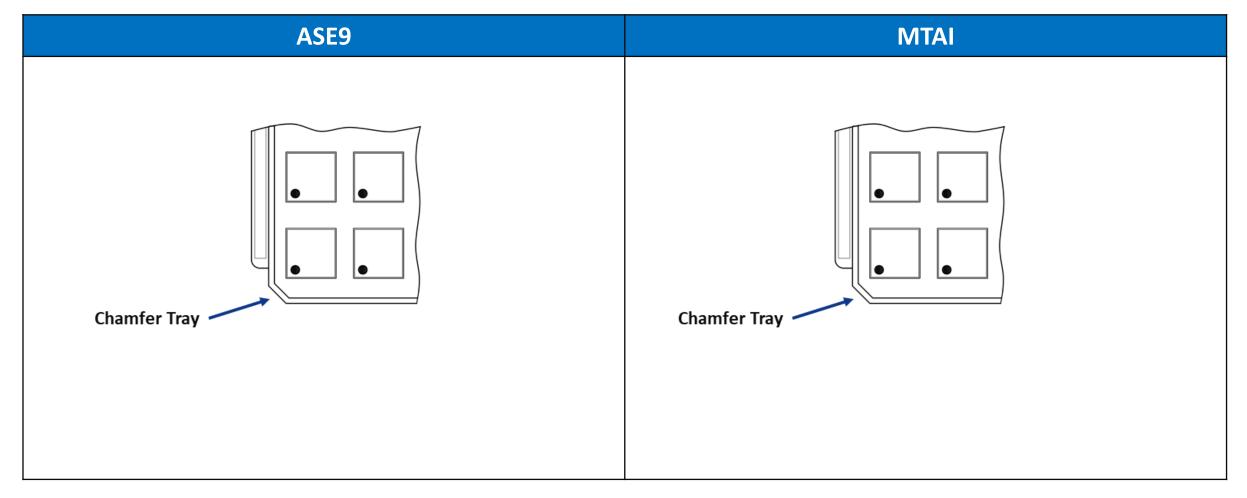
Pre and Post Change Summary – (36L FCCSP) Tray



Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Color	Tray Stack
ASE9	150C	13	32	416	Black	5+1
MTAI	150C	13	32	416	Black	5+1

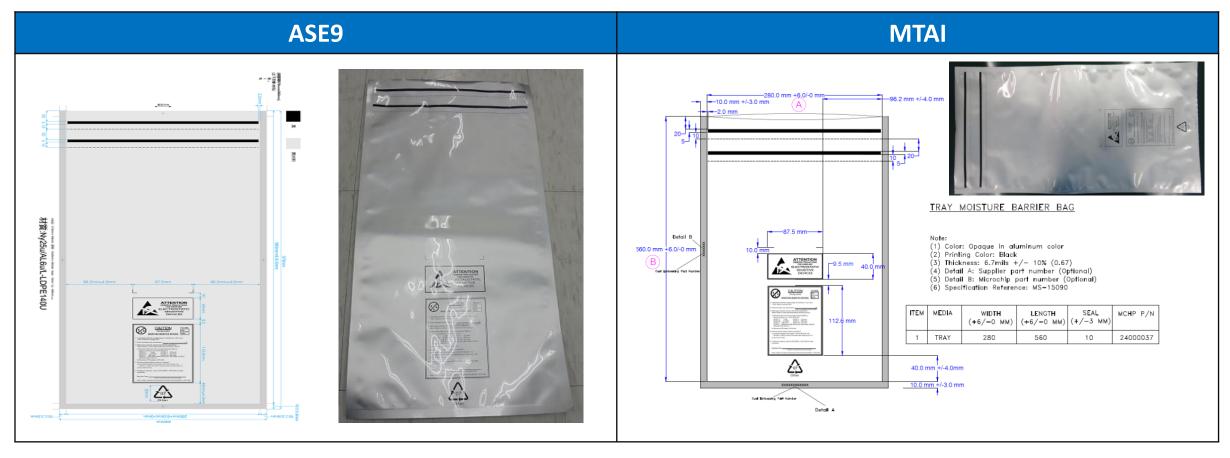


Pre and Post Change Summary – (36L FCCSP) Tray Pin 1 Orientation





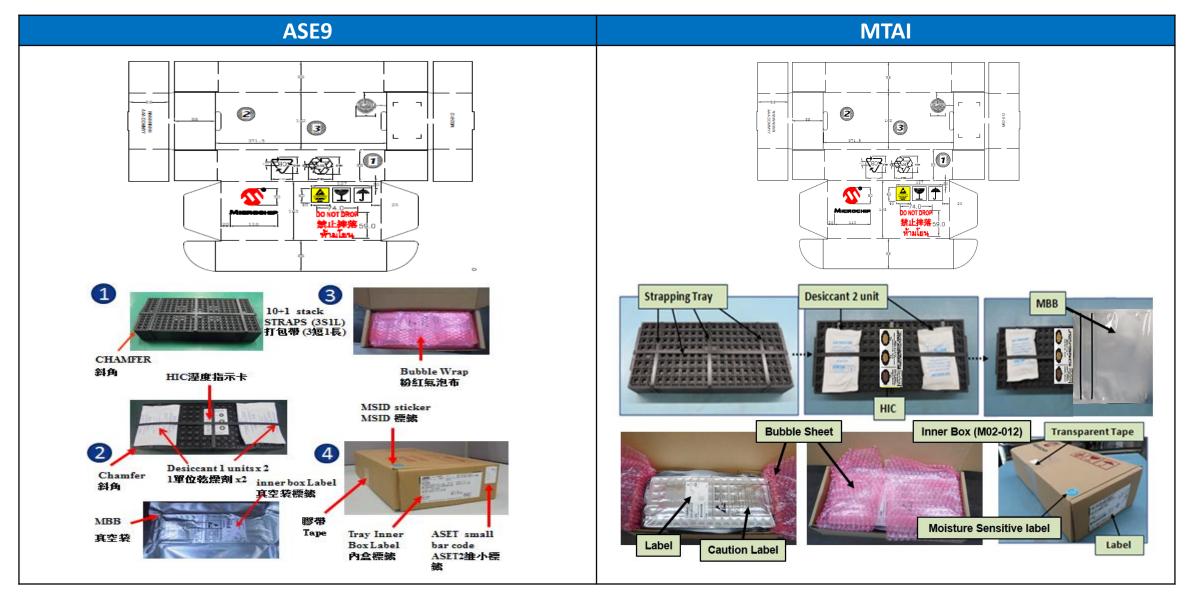
Pre and Post Change Summary – (36L FCCSP) Moisture Barrier Bag (MBB)



Plant	Length (mm)	Width (mm)	Thickness (mm)
ASE9	570	300	0.18
MTAI	560	280	0.1702



Pre and Post Change Summary – (36L FCCSP) Tray Packing Method







QUALIFICATION REPORT SUMMARY

PCN #: MFOL-06WDZP834

Date: September 24, 2020

Qualification of MTAI as an additional final test site for selected Microsemi ENT products available in 138L QFN package. Microsemi ENT VSC849xxx, VSC722xxx, VSC751xxx, VSC848xxx, VSC334xxx, VSC822xxx, VSC824xxx and VSC865xxx device families available in 196L FCBGA, 144L FCCSP, 324L, 484L and 780L HFCBGA, 444L HSBGA, 64L TQFP and 172L VQFN packages. This is a qualification by similarity (QBS).

- Purpose: Qualification of MTAI as an additional final test site for selected Microsemi ENT VSC849xxx, VSC722xxx, VSC751xxx, VSC848xxx, VSC334xxx, VSC822xxx, VSC824xxx and VSC865xxx device families available in 196L FCBGA, 144L FCCSP, 324L, 484L and 780L HFCBGA, 444L HSBGA, 64L TQFP and 172L VQFN packages. This is a qualification by similarity (QBS).
- CCB No.: 3740, 3740.001, 3740.002, 3740.003, 3740.004 and 3740.007

Test / Evaluation	Test Conditions / Parameters	Result
Test comparison	 Select 50 good sample - test using the original platform and retest using destination platform. The selected measured parameter should be within +/-10% variation between original and destination platform. 	Passed
Fresh lot run	 Select 1 fresh lot. Lot quantity is 3,000 units. Test using the new test location platform. Then cross correlate with original test location platform. Bin to bin difference should be within 0.1%. 	Passed

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Affected Catalog Part Numbers (CPN)

VSC8115XYA-05-T VSC8115XYA-06-T VSC3303YHV-01 VSC3304YHV-01